

Material Declaration



Package Type	SMD
Package Size	12.9 x 4.7 mm
Terminal Finish	Matte Tin
Finish Thickness	8 microns
Weight (mg)	424.76
MSL	1

Series	CSM4
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Item	Material	Element	Content (mg)	Content (wt%)	CAS #	
Cover	Nickel Silver	Nickel (Ni)	17.006	4.004%	7440-02-0	
		Copper (Cu)	64.755	15.245%	7440-50-8	
		Iron (Fe)	0.262	0.062%	7439-89-6	
		Zinc (Zn)	21.585	5.082%	7440-66-6	
		Manganese (Mn)	0.654	0.154%	7439-96-5	
Base	SPCC	Iron (Fe)	200.742	47.260%	7439-89-6	
		Silicon (Si)	1.962	0.462%	7440-21-3	
		Carbon C	0.057	0.013%	7440-44-0	
	Kovar	Iron (Fe)	21.001	4.944%	7439-89-6	
		Nickel (Ni)	11.480	2.703%	7440-02-0	
		Cobalt (Co)	6.700	1.577%	7440-48-4	
	Solder Plating	Tin (Sn)	0.065	0.015%	7440-31-5	
	Crystal mount		Copper (Cu)	3.702	0.872%	7440-50-8
			Nickel (Ni)	1.154	0.272%	7440-02-0
			Manganese (Mn)	0.006	0.001%	7439-96-5
			Iron (Fe)	0.001	0.000%	7439-89-6
			Zinc (Zn)	1.676	0.395%	7440-66-6
	Glass		Silicon Dioxide (SiO ₂)	4.360	1.026%	14808-60-7
			Boron Oxide (B ₂ O ₃)	1.122	0.264%	1303-86-2
			Aluminum Oxide (Al ₂ O ₃)	0.463	0.109%	1344-28-1
			Lithium Oxide (Li ₂ O)	0.463	0.109%	12057-24-8
			Sodium Oxide (Na ₂ O)	0.066	0.016%	1313-59-3
Potassium Oxide (K ₂ O)			0.066	0.016%	12136-45-7	
Crystal	Crystal	Silicon Dioxide (SiO ₂)	19.623	4.620%	14808-60-7	
	Electrode	Silver (Ag)	3.925	0.924%	7440-22-4	
	Adhesive	Silver (Ag)	6.868	1.617%	7440-22-4	
		Ethylene glycol monobutyl ether acetate	0.458	0.108%	112-07-2	
		Diethylene glycol monomethyl ether acetate	0.458	0.108%	629-38-9	
		Epoxy Resin	1.374	0.323%	1	
Spacer	PPS	Polyphenol Sulfide Resin	32.705	7.700%		
Total			424.76	100.000%		



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